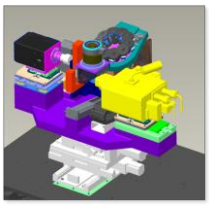

HAMAMATSU
PHOTON IS OUR BUSINESS

16 ème ATELIERS ANADEF du 5 au 8 juin 2018

*What is the Hamamatsu **RULE** within your FA FLOW* ?

FAILURE LOCALISATION is our Core Business

*What is our **VALUE** for your activities* ?

1. ***SAVE TIME*** , thanks to the RELIABILITY of our performances from the more advanced tools until low cost configurations
2. ***APPRECIATE ERGONOMY*** , thanks to the EASINESS of use of our tools from advanced users to occasional an/or multiple users within your organization
3. ***SAVE COST*** , thanks to the competitive operating cost of our tools and total cost of ownership of our solutions over years including new ambition related to the obsolescence management.

Who are our customers and partners ?

Adressing FA localization issues in your core activity within the industry chain value your are involved in.

1. ***Research*** (Technological bricks)
2. ***IDM's*** (IC's manufacturers Foundry to Fabless)
3. ***OSAT's*** (Original Semiconductors Assembly & Tests)
4. ***EMS*** (Electronics Manufacturing Services)
5. ***Tier Manufacturers*** (Modules and Equipment manufacturers)
6. ***OEM Manufacturers*** (Automotive, Aerospatial , Energy , …)

*What our **LATEST** **TECHNOLOGIES & TOOLS & DEVELOPMENTS are doing for you ?***

1. ***Lock-in Thermography*** (**New THERMAL F1**, Large FOV , Shorter TAT, 14 000 hours cooler lifetime,...)
2. ***Emission & Laser Microscopy for VISIBLE & NIR*** (**New "iPHEMOS_MP"** , **New "iPHEMOS_DD"** including **New Laser Scanner**, **New Nanolens VIS_WR** with Tilt correction stage, to adress higher spatial resolution (below 28nm) or Wide Band Gap devices (Power Devices) and actual technologies (NIR inspection)
3. ***Laser Probing*** **New updates features for EOP/EOFM** (Frequency wider bandwidth (KHz to few 30GHz), CAD links, Sequential EOP, Sampling weight, Trigger setting including High impedance input up to 10Kohm, Filtering ,....)
4. ***Time Resolved TR LADA*** (Resolution higher than optical spot , higher CAD alignment, ...)
5. ***New OBIRCH amp***, for OBIRCH, OBIC , LADA , SDL (4 quadrants with Higher Sensitive Mode and Lower noise)
6. ***New Developments*** (**MOCI** to address low resistance short & opens failures , **SOBIRCH** for 3D Memories & Stacked packages)(MOCI is magnetic approach , SOBIRCH is ultra_sonic approach)
7. ***Our Tools are adressing DIES or WAFER levels , PACKAGES levels , BOARDS levels***

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